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(71) 申请人: 北京北方华创微电子装备有限公司 (**BEIJING NAURA MICROELECTRONICS EQUIPMENT CO., LTD.**) [CN/CN]; 中国北京市大兴区北京经济技术开发区文昌大道8号 100176 (CN)。

(72) 发明人:张云龙(**ZHANG, Yunlong**); 中国北京市大兴区北京经济技术开发区文昌大道8号 100176 (CN)。 刘红丽(**LIU, Hongli**); 中国北京市大兴区北京经济技术开发区文昌大道8号 100176 (CN)。

(74) 代理人: 北京天昊联合知识产权代理有限公司 (**TEE & HOWE INTELLECTUAL PROPERTY ATTORNEYS**); 中国北京市东城区东长安街1号东方广场东方经贸城西一办公楼5层1, 6-12室 100738 (CN)。

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(54) **Title:** SUPPORT DEVICE, HEATER AND SEMICONDUCTOR PROCESS APPARATUS

(54) 发明名称: 支撑装置、加热器和半导体工艺设备

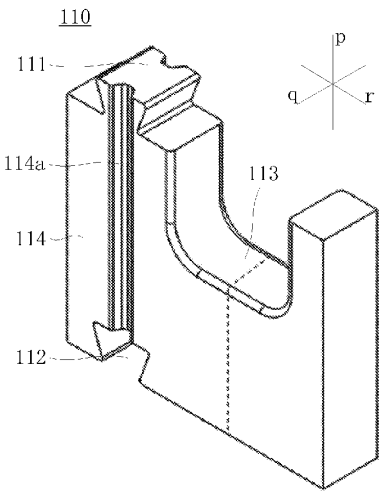


图 1

(57) **Abstract:** Disclosed in the present application are a support device, a heater and a semiconductor process apparatus. The disclosed support device is applied to a heater of the semiconductor process apparatus to support heating bodies of the heater, and comprises a plurality of support units, which are arranged in a surrounding manner, wherein each support unit comprises a plurality of insulating support bodies stacked in sequence; a first limiting portion is provided at a first end portion of each insulating support body; a second limiting portion is provided at a second end portion of each insulating support body facing away from the corresponding first end portion; the first limiting portion of one of any two adjacent insulating support bodies in each support unit is in limiting fit with the second limiting portion of the other one of the two insulating support bodies in a first axis direction; the insulating support bodies are configured to be in support fit with the heating bodies; and the first axis direction is parallel to the stacking direction of the plurality of insulating support bodies. The solution can solve the problem in the related art of heating bodies being prone to experiencing deformation after the deformation of a heating body support device caused by thermal expansion and contraction.

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CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG)。

本国际公布:

— 包括国际检索报告(条约第21条(3))。

(57) 摘要: 本申请公开一种支撑装置、加热器和半导体工艺设备，所公开的支撑装置，应用于半导体工艺设备的加热器，以对加热器的加热体进行支撑，所公开的支撑装置包括多个支撑单元，多个支撑单元环绕设置，每个支撑单元均包括多个依次叠置的绝缘支撑体，每个绝缘支撑体的第一端部均设有第一限位部，绝缘支撑体的与第一端部相背的第二端部设有第二限位部；在每个支撑单元中任意相邻的两个绝缘支撑体中的一者的第一限位部与另一者的第二限位部沿第一轴线方向限位配合，绝缘支撑体用于与加热体支撑配合，其中，第一轴线方向与多个绝缘支撑体的叠置方向平行。上述方案可以解决相关技术中的加热体支撑装置在热胀冷缩变形后容易造成加热体变形的问题。